Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	6	("5027191" "6483187" "6525942"). PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 11:49
S2	4	("6020629" "6528882").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 11:49
S3	9	("4835598" "5130771" "5640048" "5959356" "6206997" "6282094" "6325272").PN. OR ("6528882"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/06 11:50
S4	27	("5285352" "5583377" "5642261" "5741729" "5825628" "5942795" "5959356" "6008536" "6023098" "6034427" "6038137" "6117705" "6125042").PN. OR ("6282094"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/06 11:50
S5	9	("5027191" "5710459" "5741729" "6212076" "6282094" "6483187" "6525942" "6657864" "6882537").PN. OR ("6954360"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/06 11:51
S6	6	S5 not S1	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/06 11:51
S7	9	("5027191" "5710459" "5741729" "6212076" "6282094" "6483187" "6525942" "6657864" "6882537").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/06 14:13
S8	0	(3061/704).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 14:13
S9	2610	(361/704).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 14:20
S10	108	S9 and die with pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 14:23

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S11	513	(257/670).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 14:23
S12	16888	pad with finger	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:22
S13	47	S11 and pad with finger	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 14:30
S14	9273	(257/66\$1).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:19
S15	308	S14 and pad near5 finger	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 14:57
S16	284	S15 not S13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 14:30
S17	234	S15 not S13	USPAT	OR	ON	2006/02/06 14:30
S18	54	("5479050" "5594234" "5663597").PN. OR ("6211462"). URPN.	US-PGPUB; USPAT; USOCR	OR ·	ON	2006/02/06 14:40
S19	8251	(257/67\$1).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 15:20
S20	340	S19 and pad near5 finger	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 14:57

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S21	171	S20 not S15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 14:57
S22	16888	pad with finger	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:19
S23	10981	pad near5 finger	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:21
S24	8251	S19 S11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:20
S25	340	S24 and S23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:22
S26	o	S25 not (S21 S18 S16 S15)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:22
S27	7064	pad near5 tip	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:21
S28	696	S27 and S23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:22
S29	665	S28 not (S21 S18 S16 S15)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:28

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S30	6241	S27 not S12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:23
S31	167	S24 and S30	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 15:23
S32	167	S31 not (S21 S18 S16 S15)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:15
S33	2351	(IC chip die integrated near1 circuit semiconductor siliocn) near2 pad near5 (phalange thumb tip finger tip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:17
S34	1976	S33 not S24	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:18
S35	2005	(IC chip die integrated near1 circuit semiconductor siliocn) near2 pad near4 (phalange thumb tip finger tip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:32
S36	1673	S35 not S24	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:18
S37	629	(IC chip die integrated near1 circuit semiconductor siliocn) near1 pad with (extend\$3 attach\$3 prolong\$3) with (phalange thumb tip finger tip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:21
S38	14388	((IC chip die integrated near1 circuit semiconductor siliocn) near1 pad). ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:21

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S39	252	S37 and S38	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:27
S40	202	S39 not (S21 S18 S16 S15 S32)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:22
S41	130	S39 and (PCB board BGA)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:35
S42	103	S41 not (S21 S18 S16 S15)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:33
S43	471	((IC chip die integrated near1 circuit semiconductor siliocn) near2 pad near4 (phalange thumb tip finger tip)).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 17:04
S44	362	S43 not (S40 S21 S18 S16 S15)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:34
S45	1	S41 and S44	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:34
S46	80	S44 and (PCB board BGA)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:40
S47	1360	((IC chip die integrated near1 circuit semiconductor siliocn) with pad with (phalange thumb tip finger tip))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:38
S48	836	((IC chip die integrated near1 circuit semiconductor siliocn) near2 pad with (phalange thumb tip finger tip))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:39

S49	1793943	((IC chip die integrated near1 circuit semiconductor siliocn) near1pad with (phalange thumb tip finger tip))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:39
S50	570	((IC chip die integrated near1 circuit semiconductor siliocn) near1 pad with (phalange thumb tip finger tip))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 17:04
S51	373	S50 not S44	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:40
S52	76	S50 and (PCB board BGA)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 16:40
S53	12	("4362899" "4890155" "5194833").PN. OR ("5373187"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/06 16:45
S54	183	(IC chip die integrated near1 circuit semiconductor siliocn) near2 pad same PWB	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 17:04
S55	0	((IC chip die integrated near1 circuit semiconductor siliocn) near1 pad with (phalange thumb tip finger tip)) same PWB	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 17:05
S56	23	((IC chip die integrated near1 circuit semiconductor siliocn) near1 pad with (phalange thumb tip finger tip)) same PWB	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/06 17:05
S57	25	("4551746" "4551747" "5089881" "5218230" "5513076").PN. OR ("5691568").URPN.	US-PGPUB; USPAT; USOCR	OR.	ON	2006/02/06 17:08
S58	54	("5519576" "5672909" "5691568").PN. OR ("5903050"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/06 17:16

559	297		305" "2001 554" "20020		US-PGPUB; USPAT;	OR	ON	2006/02/06 17:25
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		"4727633"	"4737839"	<i>"4756080"</i>				
		"4812896"	"4862245"	"4862246"				
		"4907067"	"4916519"	"4920074"				
		"4935803"	"4942454"	"4987475"				
		"5018003"	"5029386" i	"5041902"				
		"5057900" i	"5059379" i	"5065223" j				
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S60	1	"5594234".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/06 17:26
S61	28	("4714952" "5252783" "5428248" "5436500" "5440170").PN. OR ("5594234").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/06 20:04
S62	2338	(257/676).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 20:05
S63	1330	(257/691).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/06 20:05